

2A, 50V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- Low power loss, high efficiency
- Ideal for automated placement
- Glass passivated junction chip
- Fast switching for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Packing code with suffix "G" means green compound (halogen-free)
- Part no. with suffix "H" means AEC-Q101 qualified
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.09 g (approximately)

KEY PARAMETERS						
PARAMETER	VALUE	UNIT				
I _{F(AV)}	2	Α				
V_{RRM}	50 - 1000	V				
I _{FSM}	50	Α				
T_{JMAX}	150	°C				
Package	DO-214AA (SMB)					
Configuration	Single Die					

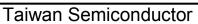




DO-214AA (SMB)

PARAMETER	SYMBOL	HS2A	HS2B	HS2D	HS2F	HS2G	HS2J	HS2K	HS2M	UNIT
Marking code on the device		HS2A	HS2B	HS2D	HS2F	HS2G	HS2J	HS2K	HS2M	
Repetitive peak reverse voltage	V_{RRM}	50	100	200	300	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	210	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	300	400	600	800	1000	V
Forward current	I _{F(AV)}	2				Α				
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}	50					А			
Junction temperature	T _J	- 55 to +150			°C					
Storage temperature	T _{STG}	- 55 to +150					°C			

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THERMAL PERFORMANCE								
PARAMETER	SYMBOL	LIMIT	UNIT					
Junction to Ambient Thermal Resistance	R _{eJA}	80	°C/W					

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
HS2A				-		V
	HS2B			-	1.0	V
	HS2D	I _F = 2A,T _J = 25°C		-	1.0	V
(1)	HS2F			-		V
Forward voltage per diode (1)	HS2G		V_{F}	-	1.3	V
	HS2J			-		V
	HS2K			- 1.7	1.7	V
	HS2M			-	-	V
- 10 11V	(2)	T _J = 25°C		-	5	μA
Reverse current @ rated V_R per	diode (=)	T _J = 125°C	I _R	-	150	μA
	HS2A		CJ	50	-	pF
	HS2B	1 MHz, V _R =4.0V			-	pF
	HS2D				-	pF
	HS2F				-	pF
Junction capacitance	HS2G				-	pF
	HS2J			30	-	pF
	HS2K				-	pF
	HS2M	1			-	pF
	HS2A			-		ns
	HS2B	1		-	1	ns
	HS2D	1		- 50	50	ns
	HS2F	I _F =0.5A ,I _R =1.0A		-		ns
Reverse recovery time	HS2G	I _{RR} =0.25A	t _{rr}	-	=	ns
	HS2J	-		-		ns
	HS2K			_	75	ns
	HS2M	1		-	1	ns

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms



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DRDERING INFORMATION								
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING			
	Н	R5	G	SMB	850 / 7" Plastic reel			
HS2x (Note 1)		R4		SMB	3,000 / 13" Paper reel			
(11010 1)		M4		SMB	3,000 / 13" Plastic reel			

Note:

^{*:} Optional available

EXAMPLE P/N							
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION		
HS2JHR5G	HS2J	Н	R5	G	AEC-Q101 qualified Green compound		

^{1. &}quot;x" defines voltage from 50V (HS2A) to 1000V (HS2M)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig1. Forward Current Derating Curve

3 AVERAGE FORWARD CURRENT (A) 2.5 2 1.5 1 0.5 0 25 50 75 100 150 0 125 LEAD TEMPERATURE (°C)

Fig2. Typical Junction Capacitance

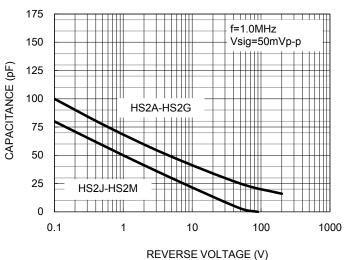


Fig3. Typical Reverse Characteristics

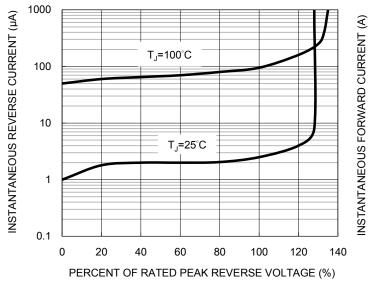
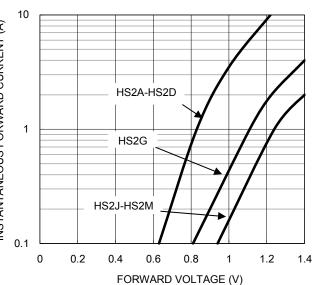


Fig4. Typical Forward Characteristics



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Fig5. Maximum Non-repetitive Forward Surge Current

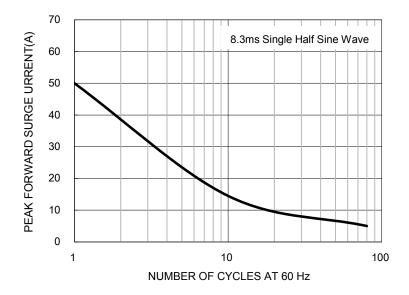
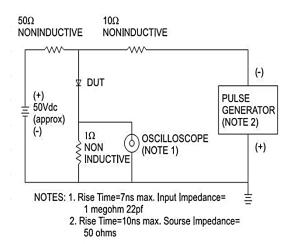
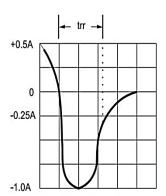


Fig6. Reverse Recovery Time Characteristic And Test Circuit Diagram

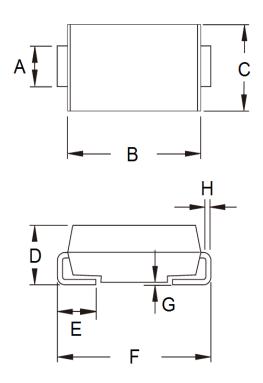






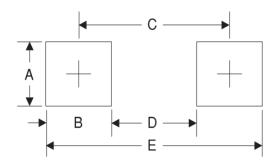
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	1.95	2.20	0.077	0.087	
В	4.05	4.60	0.159	0.181	
С	3.30	3.95	0.130	0.156	
D	1.95	2.65	0.077	0.104	
Е	0.75	1.60	0.030	0.063	
F	5.10	5.60	0.201	0.220	
G	0.05	0.20	0.002	0.008	
Н	0.15	0.31	0.006	0.012	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
В	2.5	0.098
С	4.3	0.169
D	1.8	0.071
E	6.8	0.268

MARKING DIAGRAM



P/N = Marking Code
G = Green Compound
YW = Date Code
F = Factory Code



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